MKP Film Capacitor

Material Data Sheet

Product Class	**MKP Film Capacitor B32340_343xx PFC**
Date	**18/11/2019**
IMDS ID if available	**NA**
Version	**5.02.1a (03/2019)**

Product Part (IMDS: semi component)	**Material Class** (IMDS: Material)	**Material (Classification)** VDA 231	**Substance**	TMPS**) [wt%]	**CAS if applicable**	**typical mass of material [wt-%]**	**Traces see 1)**
Active Part	Thermoplastic	2A	PP	100	9003-07-0	45.4	
	Heavy metal	1C	Zn	100	7440-66-6	4	
Encapsulation	Thermoplastic	2A	PA66	100	32131-17-2	4,05	
	Thermoplastic	2A	PBT	100	26062-94-2	4,95	
	Thermoplastic	2A	PP	100	9003-07-0	1,65	
	Duromer	2C	Polyurethane resin	100	9009-54-5	34,62	
	Light Metal	1B	Aluminum	100	7429-90-5	10,95	
	Paper, Cardboard	6D	Cellulose	100	9004-34-6	0,46	
	Elastomer	2B	Poly(ethylene-co-propylene-co-5methylene-2-norbornene	100	25038-36-2	1.0	
Termination	Mineral material	3B	Ceramic	100	13376-74-4	2	
	Heavy Metals	1C	Brass Alloy	97			
		1C	Pb	3	7439-92-2		
	Iron and Steel	1A	Steel	92	7439-89-6	2,26	
	Heavy Metal	1C	Tin	8	7440-31-5	0,3	
					Sum in total:	100	

sizes [dxh]	weight range [g.]	sizes [dxh]	weight range [g]	sizes [dxh]	weight range [g]	sizes [.....]	weight range [..]	part numbers
79,5 x 138	0,4	89,5 x 198	0,8	89,5 x 348	1,5			B32344
79,5 x 160	0,51	89,5 x 198	0,91	89,5 x 348	1,35			
79,5 x 160	0,55	89,5 x 198	1,0	89,5 x 348	1,2			
79,5 x 160	0,50	89,5 x 198	1,5	89,5 x 348	1,8			
79,5 x 160	0,6	89,5 x 273	1,2					
79,5 x 198	0,6	89,5 x 273	1,5					
79,5 x 198	0,61	89,5 x 273	1,0					
79,5 x 198	0,8							
79,5 x 198	1,0							

Not Part of a Product Class

Contact	Perosa, Eduardo
Division	CAP FILM, (GTI EPQM)
Address	TDK Electronics do Brasil Ltda, Bernardo Joaquim Ferreira, 624 – Gravataí, RS, Brazil
	Tel: +55 51 3484 7337 mailto: eduardo.perosa@tdk-electronics.tdk.com

*) others: .(not declarable or prohibited substances acc. GADSL)

**) typical mass percentage of substance

Important remarks:

1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated.

2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (☑ valid ☐ not valid)

☑ **no exemptions;**
☐ Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;
☐ Exemption 6 (b): Lead as an alloying element in aluminum containing up to 0,4 % lead by weight;
☑ Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;
☐ Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);
☐ Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;
☐ Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;
☐ Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;
☐ Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;
☐ Other Exemption than above ....